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Substitute or form 1449A/PTO Complete <u>if</u> Known_ INFORMATION DISCLOSURE **Application Number** 10/602,315 STATEMENT BY APPLICANT (USE as many sheets as necessary) Filing Date June 24, 2003 Ahn, Kie **First Named Inventor Group Art Unit** 2829 **Examiner Name** Sarkar, Asok Attorney Docket No: 1303.107US1 Sheet 1 of 4

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	First Named Inventor	Ahn, Kie		
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	Examiner Name	Sarkar, Asok		
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